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## **CLAIMS**

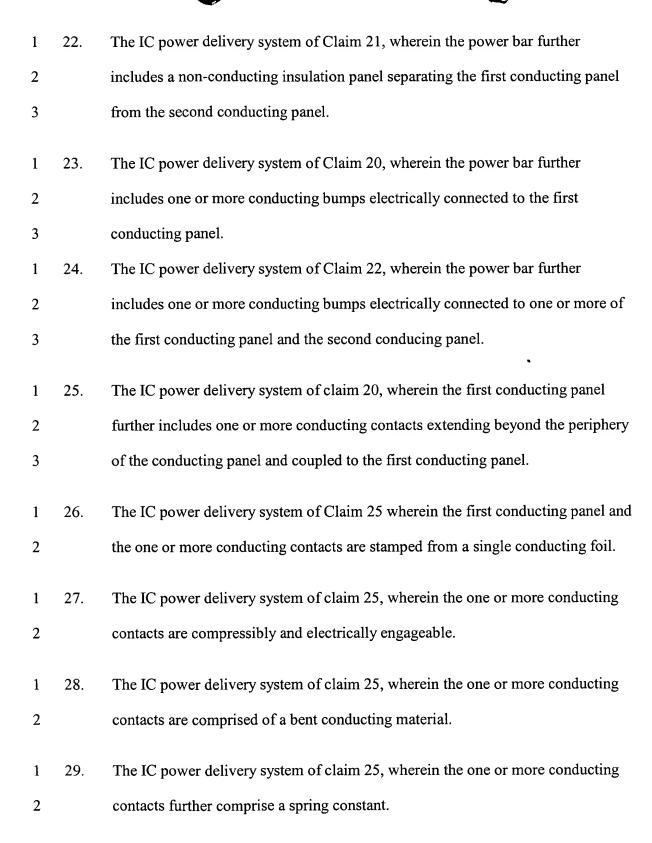
## What is claimed is:

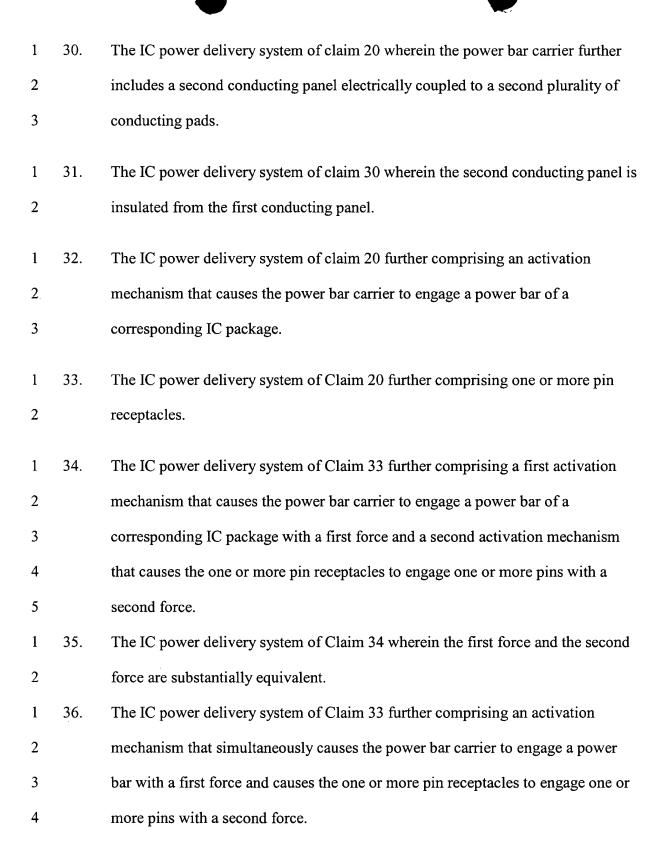
1	1.	An integrated	circuit (IC)	nackage	comprising:
1	1.	\1 m mogratou	chount (10)	, package	comprising.

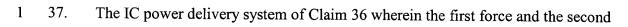
- 2 a first power plane; and
- a power bar including a first conducting panel electrically connected to the first
- 4 power plane along a first adjacent edge.
- 1 2. The IC package of claim 1 wherein the IC package further includes
- a second power plane electrically isolated from the first power plane; and
- a second conducting panel electrically connected to the second power plane of the
- 4 IC package along a second adjacent edge.
- 1 3. The IC package of Claim 2, wherein the power bar further includes a non-
- 2 conducting insulation panel separating the first conducting panel from the second
- 3 conducting panel.
- 1 4. The IC package of Claim 1, wherein the power bar further includes one or more
- 2 conducting bumps electrically connected to the first conducting panel.
- 1 5. The IC package of Claim 3, wherein the power bar further includes one or more
- 2 conducting bumps electrically connected to one or more of the first conducting
- panel and the second conducing panel.
  - 6 An Integrated Circuit (IC) socket comprising:

- a power bar carrier, wherein the power bar carrier includes a first conducting
  panel electrically coupled to a first plurality of conducting pads.
- The IC socket of claim 6, wherein the first conducting panel further includes one or more conducting contacts extending beyond the periphery of the conducting panel and coupled to the first conducting panel.
- 1 8. The socket of Claim 7 wherein the first conducting panel and the one or more conducting contacts are stamped from a single conducting foil.
- 1 9. The IC socket of claim 7, wherein the one or more conducting contacts are compressibly and electrically engageable.
- 1 10. The IC socket of claim 7, wherein the one or more conducting contacts are comprised of a bent conducting material.
- 1 11. The IC socket of claim 7, wherein the one or more conducting contacts further comprise a spring constant.
- 1 12. The IC socket of claim 6 wherein the power bar carrier further includes a second conducting panel electrically coupled to a second plurality of conducting pads.
- 1 13. The IC socket of claim 12 wherein the second conducting panel is insulated from the first conducting panel.
- 1 14. The IC socket of claim 6 further comprising an activation mechanism that causes 2 the power bar carrier to engage a power bar of a corresponding IC package.
- 1 15. The IC socket of Claim 6 further comprising one or more pin receptacles.

1	16.	The IC socket of Claim 15 further comprising a first activation mechanism that
2		causes the power bar carrier to engage a power bar of a corresponding IC package
3		with a first force and a second activation mechanism that causes the one or more
4		pin receptacles to engage one or more pins with a second force.
1	17.	The IC socket of Claim 16 wherein the first force and the second force are
2		substantially equivalent.
1	18.	The IC socket of Claim 15 further comprising an activation mechanism that
2		simultaneously causes the power bar carrier to engage a power bar with a first
3		force and causes the one or more pin receptacles to engage one or more pins with
4		a second force.
1	19.	The IC socket of Claim 18 wherein the first force and the second force are
2		substantially equivalent.
1	20.	An integrated circuit (IC) power delivery system comprising:
2		an IC socket including a power bar carrier comprising a first conducting panel
3		electrically coupled to a first plurality of conducting pads; and
4	-	an IC package including a first power plane and a power bar comprising a first
5		conducting panel electrically connected to the first power plane along a
6		first adjacent edge.
1	21.	The IC power delivery system of claim 20 wherein the IC package further
2.	21,	includes:
2.		
3		a second power plane electrically isolated from the first power plane; and
4		a second conducting panel electrically connected to the second power plane of the
5		IC package along a second adjacent edge.







2 force are substantially equivalent.